WHAT IS CLAIMED IS:

1. A semiconductor module, comprising:

a heat spreader;

at least two semiconductors thermally coupled to said heat spreader;

a plurality of electrically conductive leads electrically connected to said semiconductors, where at least one of said electrically conductive leads is common to both of said semiconductors; and

a termination resistor electrically coupled to at least one of said semiconductors.

2. A semiconductor module according to claim 1, wherein said semiconductors are electrically coupled to one another in series, and where said semiconductors are capable of being electrically coupled to a transmission channel.

3. A semiconductor module according to claim 2, wherein a final semiconductor in said series, remote from said transmission channel, is electrically coupled to said termination resistor.

4. A semiconductor module according to claim 1, wherein one semiconductor of the semiconductors is not connected to said termination resistor, and an additional termination resistor is electrically coupled to the one semiconductor not connected to said termination resistor.

5. A semiconductor module according to claim 1, wherein a resistance value of the termination resistor is selected such that an impedance of said termination resistor substantially matches an impedance of a transmission channel and a signal source to which said termination resistor is connected.

6. A semiconductor module according to claim 1, wherein said termination resistor's form of termination is selected from a group consisting of: parallel

termination, Thevenin termination, series termination, AC termination, and Schotty-diode termination.

7. A semiconductor module according to claim 1, wherein said termination resistor is thermally coupled to said heat spreader.

8. A semiconductor module according to claim 1, wherein said termination resistor is bonded directly to a side wall of said heat spreader.

9. A semiconductor module according to claim 1, wherein said two semiconductors are mounted on opposing side walls of said heat spreader.

10. A semiconductor module according to claim 2, wherein each of said semiconductors are bonded directly to said side wall of said heat spreader.

11. A semiconductor module according to claim 1, wherein said leads form part of a flexible circuit at least partially attached to said heat spreader.

12. A semiconductor module according to claim 11, wherein said flexible circuit is a flexible dielectric tape.

13. A semiconductor module according to claim 12, wherein said flexible circuit is bonded directly to said side wall of said heat spreader.

14. A semiconductor module according to claim 1, wherein said common electrically conductive lead is selected from a group consisting of a voltage supply node, a reference voltage node, and an electrical ground node.

15. A semiconductor module according to claim 1, wherein said heat spreader is a solid block of heat dissipating material.

16. A semiconductor module according to claim 1, wherein said heat spreader is "u" shaped.

17. A method of making a semiconductor module, comprising:

providing a plurality of electrically conductive leads;

electrically coupling at least two semiconductors to said plurality of electrically conductive leads, where at least one of said electrically conductive leads is common to both of said semiconductors;

thermally coupling said semiconductors to a heat spreader; and

electrically coupling a termination resistor to at least one of said semiconductors.

18. A method according to claim 17, initially comprising electrically coupling said semiconductors in series, where said semiconductors are capable of being electrically coupled to a transmission channel.

19. A method according to claim 17, further comprising electrically coupling an additional termination resistor to the semiconductor not already connected to said termination resistor, where each of said semiconductors is capable of being electrically coupled to a separate transmission channel.

20. A method according to claim 17, including bonding said termination resistor directly to a side wall of said heat spreader.

21. A method according to claim 17, including mounting said two semiconductors on opposing side walls of said heat spreader.

22. A method according to claim 17, including bonding each of said semiconductors directly to a side wall of said heat spreader.

23. A method according to claim 17, wherein said leads form part of a flexible circuit at least partially attached to said heat spreader, said method including bonding said flexible circuit directly to a side wall of said heat spreader.